

## RESIN COMPOSITION, PREPREG, AND LAMINATED SHEET

## ABSTRACT

There is provided a resin composition for printed wiring boards that, while maintaining excellent flame retardance, has excellent heat resistance, reflow resistance, and drilling workability, and, at the same time, has low water absorption without use of halogen compounds and phosphorus compounds. The resin composition comprises (A) a non-halogen epoxy resin, (B) a biphenyl aralkyl phenolic resin, (C) a maleimide compound and (D) an inorganic filler.